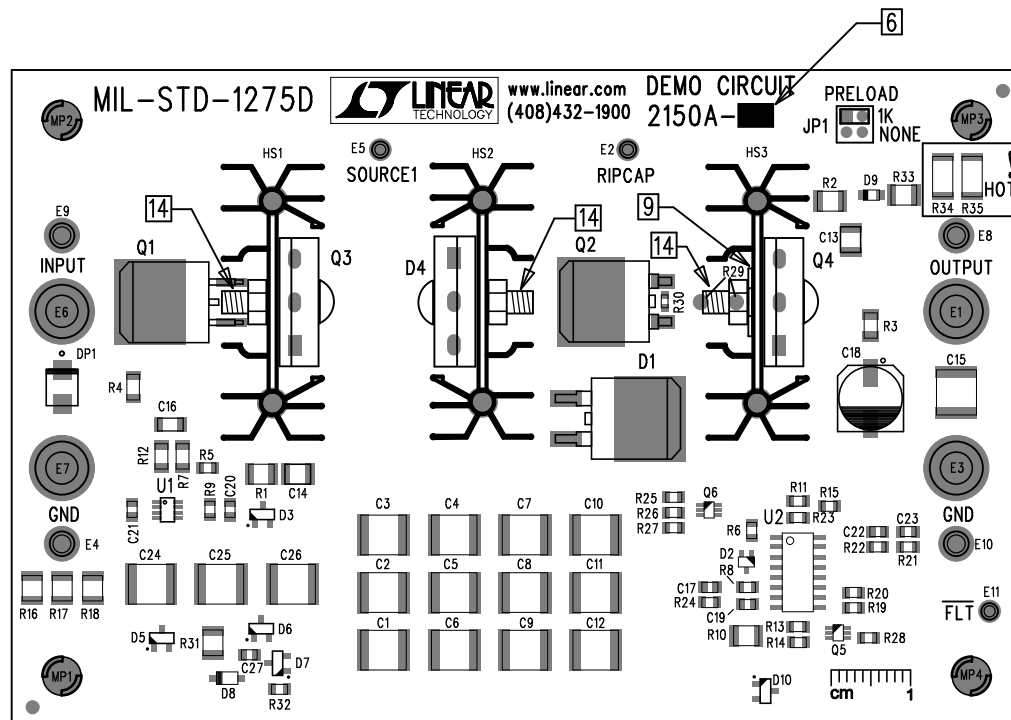


REVISION HISTORY				
ECO	REV	DESCRIPTION	APPR	DATE
-	2	PRODUCTION	D.EDDLEMAN	02-26-14



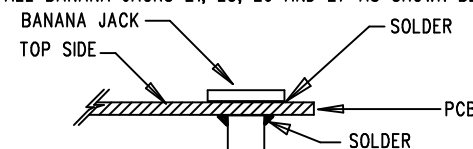
LAYER 1 - TOP LAYER  
TOP SILKSCREEN

LINEAR TECHNOLOGY  
DC2150A-2  
MIL-STD-1275D  
DATE: 04-25-2014

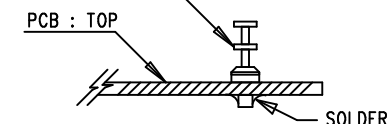
## NOTES: UNLESS OTHERWISE SPECIFIED

1. WORKMANSHIP SHALL BE IN ACCORDANCE WITH IPC-A-610.
2. ASSEMBLY PROCESS SHALL INCLUDE REFLOW SOLDER TOP SIDE SMD. MAXIMUM SOLDER TEMPERATURE SHALL BE 240 DEGREES CELSIUS.
3. OMITTED PARTS ARE SPECIFIED ON THE BILL OF MATERIALS. SUCH PARTS ARE DESIGNATED AS "OPTION" OR "NOT USED". LAND PATTERNS FOR THESE PARTS SHALL BE FREE OF SOLDER. MASK THE SOLDER STENCIL AT THESE LOCATIONS.
4. DEPANELIZE BOARDS AFTER ASSEMBLY AND ROUTE-OUT THE BREAKOUT TABS ON ALL BOARD EDGES.
5. DO NOT PUT ASSEMBLY OR QA STAMPS ON BOARD.
6. MARK EACH ASSEMBLY TYPE WITH BLACK PERMANENT MARKER.
7. INSTALL SHUNT IN JP1 IN POSITION AS DEPICTED.
8. INSTALL HEATSINKS HS1-HS3 IN CORRECT ORIENTATION AS DEPICTED.
9. THERMISTOR R29 SHALL BE MOUNTED ONTO HEATSINK HS3. THERMAL COMPOUND SHALL BE APPLIED TO COMPONENT INTERFACE.
10. Q3, Q4 AND D4 SHALL BE MOUNTED ONTO THEIR RESPECTIVE HEATSINKS, USING THE UPPERMOST HOLE IN THE HEATSINK FOR MOUNTING. THERMAL COMPOUND SHALL BE APPLIED TO COMPONENT INTERFACES.

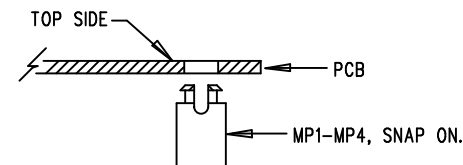
11. INSTALL BANANA JACKS E1, E3, E6 AND E7 AS SHOWN BELOW:




12. INSTALL TURRETS E2, E4, E5, AND E8-E11 AS SHOWN BELOW:  
TURRET (MIL MAX#2501, #2308 TYPES)



13. INSTALL STANDOFFS AT 4 LOCATIONS AS SHOWN BELOW:



14. MOUNT COMPONENTS TO HEATSINK USING #4-40 HARDWARE AS DEPICTED. APPLY THREADLOCK TO NUT.

APPROVALS		 1630 MCCARTHY BLVD MILPITAS, CA 95035 PH: (408)432-1900 www.linear.com LTC CONFIDENTIAL- FOR CUSTOMER USE ONLY		
PCB DES.	M. HAWKINS			
APP ENG.	D. EDDLEMAN			
		TITLE: ASSEMBLY DRAWING, TOP		
		MIL-STD-1275D		
		SIZE	IC NO. N/A	REV.
		N/A	DEMO CIRCUIT 2150A	2
SCALE = NONE		FILENAME: DC2150A-1.PCB		SHT 1 OF 1